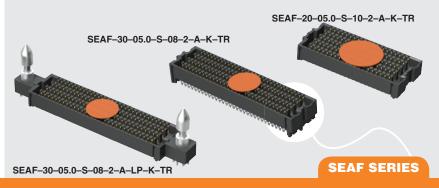


SEARAY

(1,27 mm) .050"



HIGH SPEED/HIGH DENSI OPEN BN

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SEAF

Insulator Material: Black LCP
Contact Material:
Copper Alloy
Operating Temp Range: -55°C to +125°C Current Rating (7 mm stack height): 1.8 A per pin (10 adjacent pins powered) Plating: Au or Sn over 50 μ" (1,27 μm) Ni

Lead-Free Solderable: Yes **RECOGNITIONS**

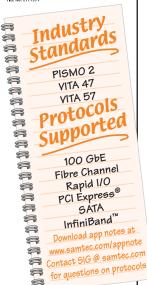
Contact Resistance: $5.5 \text{ m}\Omega$

Working Voltage: 240 VAC RoHS Compliant: Yes

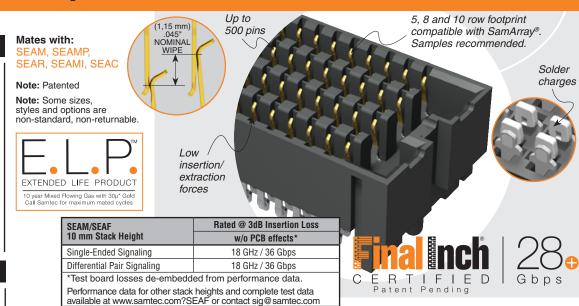
For complete scope of

recognitions see www.samtec.com/quality





MATED HEIGHTS			
SEAM	SEAF LEAD STYLE		
LEAD STYLE	-05.0	-06.0	-06.5
-02.0	7 mm	8 mm	8.5 mm
-03.0	8 mm	9 mm	9.5 mm
-03.5	8.5 mm	9.5 mm	10 mm
-06.5	11.5 mm	12.5 mm	13 mm
-07.0	12 mm	13 mm	13.5 mm
-09.0	14 mm	15 mm	15.5 mm
-11.0	16 mm	17 mm	17.5 mm



·10, –15, –20 30, -40, -50 (-10 only available in 04 row)

SEAE

NO. PINS

PER ROW

(–15 only available in 10 row and -05.0 lead style)

NO. OF ROWS	В
-04	(5,66) .223
-05, -06	(8,20) .323
-08	(10,74) .423
-10	(13,28) .523

LEAD STYLE from chart

LEAD

STYLE

PLATING

OPTION

= 10 µ"

(0,25 µm)

Gold on

contact

area,

Matte Tin on

solder tail

-S

area.

LEAD STYLE Α (5,05) .199 -05.0 (6,05 .238 -06.0(6,55) -06.5

= 30 µ" (0,76 µm) Gold on contact Matte Tin on solder tail

-04 =Four Rows -05

=Five

NO. OF

ROWS

Rows -06 =Six Rows -08

=Eight Rows -10 =Ten Rows

-1 = Tin/Lead Alloy Solder Charge

SOLDER

TYPE

-2 = Lead-Free Solder Charge

-LP = Latch Post (-LP required for SEAC mate only) (Available with 05.0 lead style and -04, -06, -08

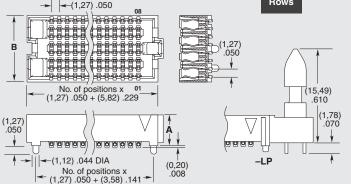
& -10 rows only)

OPTION

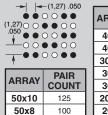
= Polyimide film Pick & Place Pad) (Not available with -10 and –15 pins with –LP Latch post)

ALSO AVAILABLE (MOQ Required)

· Polarization pin Contact Samtec.



DIFFERENTIAL



100

40x10

PΔIR ARRAY COUNT 40x8 80 40x6 60 30x10 75 30x8 60 30x6 45 20x10 50 20x8 40 20x5 25